

EXTENDED COMMON-MODE RS-485 TRANSCEIVERS

FEATURES

- **Common-Mode Voltage Range (–20 V to 25 V) More Than Doubles TIA/EIA-485 Requirement**
- **Receiver Equalization Extends Cable Length, Signaling Rate (HVD23, HVD24)**
- **Reduced Unit-Load for up to 256 Nodes**
- **Bus I/O Protection to Over 16-kV HBM**
- **Failsafe Receiver for Open-Circuit, Short-Circuit and Idle-Bus Conditions**
- **Low Standby Supply Current 1- μ A Max**
- **More Than 100 mV Receiver Hysteresis**

APPLICATIONS

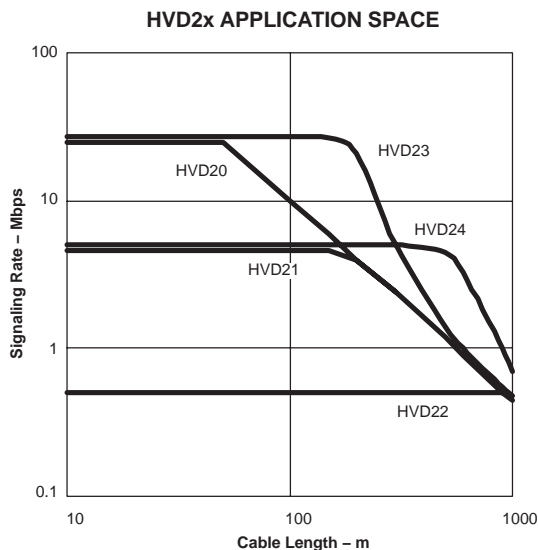
- **Long Cable Solutions**
 - **Factory Automation**
 - **Security Networks**
 - **Building HVAC**
- **Severe Electrical Environments**
 - **Electrical Power Inverters**
 - **Industrial Drives**
 - **Avionics**

DESCRIPTION

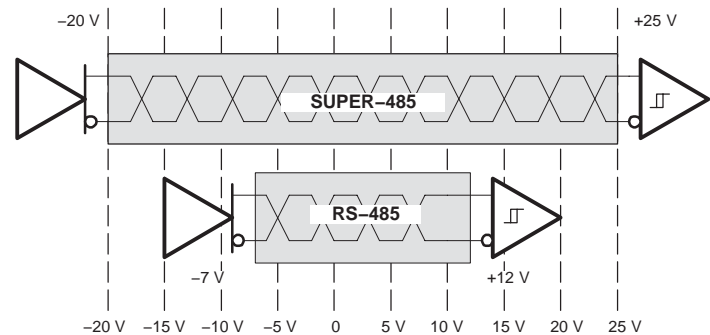
The transceivers in the HVD2x family offer performance far exceeding typical RS-485 devices. In addition to meeting all requirements of the TIA/EIA-485-A standard, the HVD2x family operates over an extended range of common-mode voltage, and has features such as high ESD protection, wide receiver hysteresis, and failsafe operation. This family of devices is ideally suited for long-cable networks, and other applications where the environment is too harsh for ordinary transceivers.

These devices are designed for bidirectional data transmission on multipoint twisted-pair cables. Example applications are digital motor controllers, remote sensors and terminals, industrial process control, security stations, and environmental control systems.

These devices combine a 3-state differential driver and a differential receiver, which operate from a single 5-V power supply. The driver differential outputs and the receiver differential inputs are connected internally to form a differential bus port that offers minimum loading to the bus. This port features an extended common-mode voltage range making the device suitable for multipoint applications over long cable runs.



HVD2x Devices Operate Over a Wider Common-Mode Voltage Range



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These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

DESCRIPTION (continued)

The 'HVD20 provides high signaling rate (up to 25 Mbps) for interconnecting networks of up to 64 nodes.

The 'HVD21 allows up to 256 connected nodes at moderate data rates (up to 5 Mbps). The driver output slew rate is controlled to provide reliable switching with shaped transitions which reduce high-frequency noise emissions.

The 'HVD22 has controlled driver output slew rate for low radiated noise in emission-sensitive applications and for improved signal quality with long stubs. Up to 256 'HVD22 nodes can be connected at signaling rates up to 500 kbps.

The 'HVD23 implements receiver equalization technology for improved jitter performance on differential bus applications with data rates up to 25 Mbps at cable lengths up to 160 meters.

The 'HVD24 implements receiver equalization technology for improved jitter performance on differential bus applications with data rates in the range of 1 Mbps to 10 Mbps at cable lengths up to 1000 meters.

The receivers also include a failsafe circuit that provides a high-level output within 250 microseconds after loss of the input signal. The most common causes of signal loss are disconnected cables, shorted lines, or the absence of any active transmitters on the bus. This feature prevents noise from being received as valid data under these fault conditions. This feature may also be used for Wired-Or bus signaling.

The SN65HVD2X devices are characterized for operation over the temperature range of –40°C to 85°C.

PRODUCT SELECTION GUIDE

PART NUMBERS	CABLE LENGTH AND SIGNALING RATE ⁽¹⁾	NODES	MARKING
SN65HVD20	Up to 50 m at 25 Mbps	Up to 64	D: VP20 P: 65HVD20
SN65HVD21	Up to 150 m at 5 Mbps (with slew rate limit)	Up to 256	D: VP21 P: 65HVD21
SN65HVD22	Up to 1200 m at 500 kbps (with slew rate limit)	Up to 256	D: VP22 P: 65HVD22
SN65HVD23	Up to 160 m at 25 Mbps (with receiver equalization)	Up to 64	D: VP23 P: 65HVD23
SN65HVD24	Up to 500 m at 3 Mbps (with receiver equalization)	Up to 256	D: VP24 P: 65HVD24

⁽¹⁾ Distance and signaling rate predictions based upon Belden 3105A cable and 15% eye pattern jitter.

AVAILABLE OPTIONS

PLASTIC THROUGH-HOLE P-PACKAGE (JEDEC MS-001)	PLASTIC SMALL-OUTLINE ⁽¹⁾ D-PACKAGE (JEDEC MS-012)
SN65HVD20P	SN65HVD20D
SN65HVD21P	SN65HVD21D
SN65HVD22P	SN65HVD22D
SN65HVD23P	SN65HVD23D
SN65HVD24P	SN65HVD24D

⁽¹⁾ Add R suffix for taped and reeled carriers.

DRIVER FUNCTION TABLE

HVD20, HVD21, HVD22				HVD23, HVD24			
INPUT	ENABLE	OUTPUTS		INPUT	ENABLE	OUTPUTS	
D	DE	A	B	D	DE	A	B
H	H	H	L	H	H	H	L
L	H	L	H	L	H	L	H
X	L	Z	Z	X	L	Z	Z
X	OPEN	Z	Z	X	OPEN	Z	Z
OPEN	H	H	L	OPEN	H	L	H

H = high level, L = low level, X = don't care, Z = high impedance (off), ? = indeterminate

RECEIVER FUNCTION TABLE

DIFFERENTIAL INPUT $V_{ID} = (V_A - V_B)$	ENABLE \overline{RE}	OUTPUT R
$0.2 V \leq V_{ID}$	L	H
$-0.2 V < V_{ID} < 0.2 V$	L	H (see Note A)
$V_{ID} \leq -0.2 V$	L	L
X	H	Z
X	OPEN	Z
Open circuit	L	H
Short Circuit	L	H
Idle (terminated) bus	L	H

H = high level, L = low level, Z = high impedance (off)

NOTE A: If the differential input V_{ID} remains within the transition range for more than 250 μ s, the integrated failsafe circuitry detects a bus fault, and set the receiver output to a high state. See Figure 15.

ABSOLUTE MAXIMUM RATINGS

over operating free-air temperature range unless otherwise noted⁽¹⁾

			SN65HVD2X
Supply voltage ⁽²⁾ , V_{CC}			-0.5 V to 7 V
Voltage at any bus I/O terminal			-27 V to 27 V
Voltage input, transient pulse, A and B, (through 100 Ω , see Figure 16)			-60 V to 60 V
Voltage input at any D, DE or \overline{RE} terminal			-0.5 V to $V_{CC} + 0.5 V$
Receiver output current, I_O			-10 mA to 10 mA
Electrostatic discharge	Human Body Model ⁽³⁾	A, B, GND	16 kV
		All pins	5 kV
	Charged-Device Model ⁽⁴⁾	All pins	1.5 kV
		Machine Model ⁽⁵⁾	All pins
Continuous total power dissipation			See Power Dissipation Rating Table
Junction temperature, T_J			150°C

(1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

(2) All voltage values, except differential I/O bus voltages, are with respect to network ground terminal.

(3) Tested in accordance with JEDEC Standard 22, Test Method A114-A.

(4) Tested in accordance with JEDEC Standard 22, Test Method C101.

(5) Tested in accordance with JEDEC Standard 22, Test Method A115-A.

POWER DISSIPATION RATINGS

PACKAGE	CIRCUIT BOARD MODEL	T _A ≤ 25°C POWER RATING	DERATING FACTOR ⁽³⁾ ABOVE T _A = 25°C	T _A = 70°C POWER RATING	T _A = 85°C POWER RATING
D	Low-K ⁽¹⁾	577 mW	4.62 mW/°C	369 mW	300 mW
	High-K ⁽²⁾	913 mW	7.3 mW/°C	584 mW	474 mW
P	Low-K ⁽¹⁾	984 mW	7.87 mW/°C	630 mW	512 mW
	High-K ⁽²⁾	1344 mW	10.8 mW/°C	860 mW	700 mW

(1) In accordance with the Low-K thermal metric definitions of EIA/JESD51-3.

(2) In accordance with the High-K thermal metric definitions of EIA/JESD51-7.

(3) This is the inverse of the junction-to-ambient thermal resistance when board-mounted and with no air flow.

THERMAL CHARACTERISTICS

PARAMETER		TEST CONDITIONS		VALUE	UNITS	
θ _{JB}	Junction-to-board thermal resistance	D		86.2	°C/W	
		P		56		
θ _{JC}	Junction-to-case thermal resistance	D		47.1		
		P		54		
P _D	Typical	HVD20	V _{CC} = 5 V, T _J = 25°C, R _L = 54 Ω, C _L = 50 pF (driver), C _L = 15 pF (receiver), 50% Duty cycle square-wave signal, Driver and receiver enabled	25 Mbps		295
		HVD21		5 Mbps		260
		HVD22		500 kbps	233	
		HVD23		25 Mbps	302	
		HVD24		5 Mbps	267	
	Worst case	HVD20		V _{CC} = 5.5 V, T _J = 125°C, R _L = 54 Ω, C _L = 50 pF, C _L = 15 pF (receiver), 50% Duty cycle square-wave signal, Driver and receiver enabled	25 Mbps	408
		HVD21			5 Mbps	342
		HVD22			500 kbps	300
		HVD23			25 Mbps	417
		HVD24			5 Mbps	352
T _{SD}	Thermal shut-down junction temperature			170	°C	

RECOMMENDED OPERATING CONDITIONS

		MIN	NOM	MAX	UNIT
Supply voltage, V _{CC}		4.5	5	5.5	V
Voltage at any bus I/O terminal	A, B	-20		25	V
High-level input voltage, V _{IH}	D, DE, \overline{RE}	2		V _{CC}	V
Low-level input voltage, V _{IL}		0		0.8	
Differential input voltage, V _{ID}	A with respect to B	-25		25	V
Output current	Driver	-110		110	mA
	Receiver	-8		8	
Operating free-air temperature, T _A ⁽¹⁾		-40		85	°C
Junction temperature, T _J		-40		130	°C

(1) Maximum free-air temperature operation is allowed as long as the device recommended junction temperature is not exceeded.

DRIVER ELECTRICAL CHARACTERISTICS

over recommended operating conditions (unless otherwise noted)⁽¹⁾

PARAMETER		TEST CONDITIONS	MIN	TYP ⁽¹⁾	MAX	UNIT
V _{IK}	Input clamp voltage	I _I = -18 mA	-1.5	0.75		V
V _O	Open-circuit output voltage	A or B, No load	0		V _{CC}	V
V _{OD(SS)}	Steady-state differential output voltage magnitude	No load (open circuit)	3.3	4.2	V _{CC}	V
		R _L = 54 Ω, See Figure 1	1.8	2.5		
		With common-mode loading, See Figure 2	1.8			
ΔV _{OD(SS)}	Change in steady-state differential output voltage between logic states	See Figure 1 and Figure 3	-0.1		0.1	V
V _{OC(SS)}	Steady-state common-mode output voltage	See Figure 1	2.1	2.5	2.9	V
ΔV _{OC(SS)}	Change in steady-state common-mode output voltage, V _{OC(H)} - V _{OC(L)}	See Figure 1 and Figure 4	-0.1		0.1	V
V _{OC(PP)}	Peak-to-peak common-mode output voltage, V _{OC(MAX)} - V _{OC(MIN)}	R _L = 54 Ω, C _L = 50 pF, See Figure 1 and Figure 4		0.35		V
V _{OD(RING)}	Differential output voltage over and under shoot	R _L = 54 Ω, C _L = 50 pF, See Figure 5			10%	
I _I	Input current	D, DE	-100		100	μA
I _{O(OFF)}	Output current with power off	V _{CC} <= 2.5 V	See receiver line input current			
I _{OZ}	High impedance state output current	DE at 0 V				
I _{OS}	Short-circuit output current	V _O = -20 V to 25 V, See Figure 9	-250		250	mA
C _{OD}	Differential output capacitance		See receiver C _I			

⁽¹⁾ All typical values are at V_{CC} = 5 V and 25°C.

DRIVER SWITCHING CHARACTERISTICS

over recommended operating conditions (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP ⁽¹⁾	MAX	UNIT	
t _{PLH}	Differential output propagation delay, low-to- high	R _L = 54 Ω, C _L = 50 pF, See Figure 3	HVD20, HVD23	6	10	20	ns
t _{PHL}	Differential output propagation delay, high-to-low		HVD21, HVD24	20	32	60	
			HVD22	160	280	500	
t _r	Differential output rise time	R _L = 54 Ω, C _L = 50 pF, See Figure 3	HVD20, HVD23	2	6	12	ns
t _f	Differential output fall time		HVD21, HVD24	20	40	60	
			HVD22	200	400	600	
t _{PZH}	Propagation delay time, high-impedance-to-high-level output	RE at 0 V, See Figure 6	HVD20, HVD23			40	ns
t _{PHZ}	Propagation delay time, high-level-output-to-high-impedance		HVD21, HVD24			100	
			HVD22			300	
t _{PZL}	Propagation delay time, high-impedance-to-low-level output	RE at 0 V, See Figure 7	HVD20, HVD23			40	ns
t _{PLZ}	Propagation delay time, low-level-output-to-high-impedance		HVD21, HVD24			100	
			HVD22			300	
t _{d(standby)}	Time from an active differential output to standby	RE at V _{CC} , See Figure 8				2	μs
t _{d(wake)}	Wake-up time from standby to an active differential output					8	μs
t _{sk(p)}	Pulse skew t _{PLH} - t _{PHL}	HVD20, HVD23				2	ns
		HVD21, HVD24				6	
		HVD22				50	

⁽¹⁾ All typical values are at V_{CC} = 5 V and 25°C.

RECEIVER ELECTRICAL CHARACTERISTICS

over recommended operating conditions

PARAMETER		TEST CONDITIONS		MIN	TYP ⁽¹⁾	MAX	UNIT
V _{IT(+)}	Positive-going differential input voltage threshold	See Figure 10	V _O = 2.4 V, I _O = -8 mA		60	200	mV
V _{IT(-)}	Negative-going differential input voltage threshold		V _O = 0.4 V, I _O = 8 mA	-200	-60		
V _{HYS}	Hysteresis voltage (V _{IT+} - V _{IT-})			100	130		mV
V _{IT(F+)}	Positive-going differential input failsafe voltage threshold	See Figure 15	V _{CM} = -7 V to 12 V	40	120	200	mV
			V _{CM} = -20 V to 25 V		120	250	
V _{IT(F-)}	Negative-going differential input failsafe voltage threshold	See Figure 15	V _{CM} = -7 V to 12 V	-200	-120	-40	mV
			V _{CM} = -20 V to 25 V	-250	-120		
V _{IK}	Input clamp voltage	I _I = -18 mA		-1.5			V
V _{OH}	High-level output voltage	V _{ID} = 200 mV, I _{OH} = -8 mA, See Figure 11		4			V
V _{OL}	Low-level output voltage	V _{ID} = -200 mV, I _{OL} = 8 mA, See Figure 11				0.4	V
I _{I(BUS)}	Bus input current (power on or power off)	V _I = -7 to 12 V, Other input = 0 V	HVD20, HVD23	-400		500	μA
			HVD21, HVD22, HVD24	-100		125	
		V _I = -20 to 25 V, Other input = 0 V	HVD20, HVD23	-800		1000	
			HVD21, HVD22, HVD24	-200		250	
I _I	Input current	RE		-100		100	μA
R _I	Input resistance	HVD20, 23		24			kΩ
		HVD21, 22, 24		96			
C _{ID}	Differential input capacitance	V _{ID} = 0.5 + 0.4 sine (2π x 1.5 x 10 ⁶ t)				20	pF

(1) All typical values are at 25°C.

RECEIVER SWITCHING CHARACTERISTICS

over recommended operating conditions

PARAMETER		TEST CONDITIONS		MIN	TYP	MAX	UNIT
t _{PLH}	Propagation delay time, low-to-high level output	See Figure 11	HVD20, HVD23		16	35	ns
t _{PHL}	Propagation delay time, high-to-low level output		HVD21, HVD22, HVD24		25	50	
t _r	Receiver output rise time	See Figure 11			2	4	ns
t _f	Receiver output fall time						
t _{PZH}	Receiver output enable time to high level	See Figure 12			90	120	ns
t _{PHZ}	Receiver output disable time from high level				16	35	
t _{PZL}	Receiver output enable time to low level	See Figure 13			90	120	ns
t _{PLZ}	Receiver output disable time from low level				16	35	
t _{r(standby)}	Time from an active receiver output to standby	See Figure 14, DE at 0 V				2	μs
t _{r(wake)}	Wake-up time from standby to an active receiver output					8	
t _{sk(p)}	Pulse skew t _{PLH} - t _{PHL}					5	ns
t _{p(set)}	Delay time, bus fail to failsafe set	See Figure 15, pulse rate = 1 kHz			250	350	μs
t _{p(reset)}	Delay time, bus recovery to failsafe reset					50	ns

RECEIVER EQUALIZATION CHARACTERISTICS(1)

over recommended operating conditions

PARAMETER		TEST CONDITIONS			MIN	TYP(2)	MAX	UNIT
t _{j(pp)}	Peak-to-peak eye-pattern jitter	Pseudo-random NRZ code with a bit pattern length of 2 ¹⁶ – 1, Belden 3105A cable, See Figure 27	25 Mbps	0 m	HVD23		2	ns
				100 m	HVD20		6	
					HVD23		3	
				150 m	HVD20		15	
					HVD23		4	
				200 m	HVD20		27	
			HVD23			8		
			10 Mbps	200 m	HVD20		22	
					HVD23		8	
				250 m	HVD20		34	
					HVD23		15	
				300 m	HVD20		49	
					HVD23		27	
			5 Mbps	500 m	HVD21		128	
					HVD24		18	
			3 Mbps	500 m	HVD20		93	
					HVD21		103	
					HVD23		90	
HVD24		16						
1 Mbps	1000 m	HVD21		216				
		HVD24		62				

(1) The HVD20 and HVD21 do not have receiver equalization, but are specified for comparison.

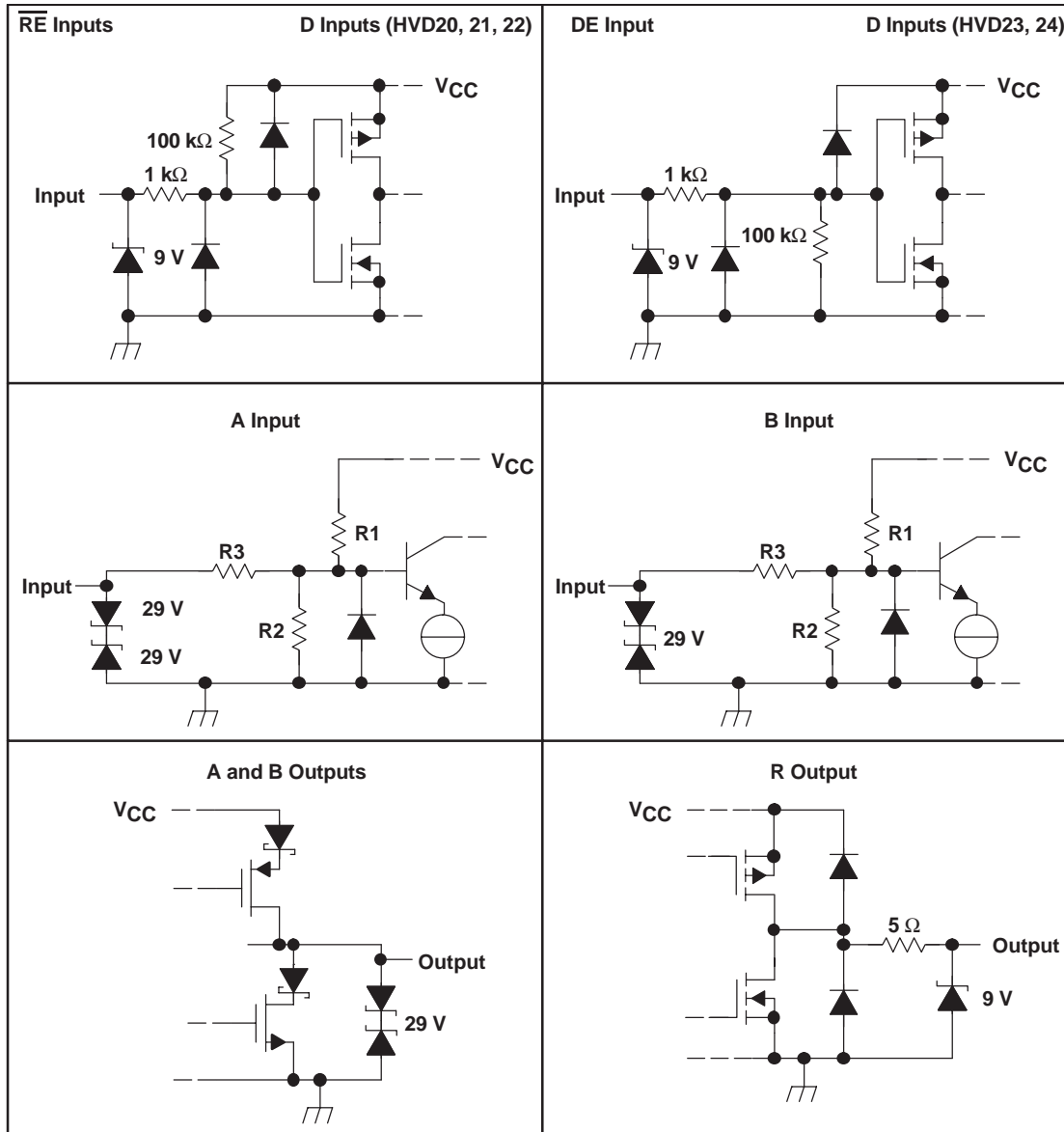
(2) All typical values are at V_{CC} = 5 V, and temperature = 25°C.

SUPPLY CURRENT

over recommended operating conditions (unless otherwise noted)

PARAMETER		TEST CONDITIONS			MIN	TYP	MAX	UNIT
I _{CC}	Supply current	Driver enabled (DE at V _{CC}), Receiver enabled (RE at 0 V) No load, V _I = 0 V or V _{CC}	HVD20		6	9	mA	
			HVD21		8	12		
			HVD22		6	9		
			HVD23		7	11		
			HVD24		10	14		
		Driver enabled (DE at V _{CC}), Receiver disabled (RE at V _{CC}) No load, V _I = 0 V or V _{CC}	HVD20		5	8	mA	
			HVD21		7	11		
			HVD22		5	8		
			HVD23		5	9		
		Driver disabled (DE at 0 V), Receiver enabled (RE at 0 V) No load	HVD20		4	7	mA	
			HVD21		5	8		
			HVD22		4	7		
			HVD23		4.5	9		
		Driver disabled (DE at 0 V), Receiver disabled (RE at V _{CC}) D open	All HVD2x				1	μA

EQUIVALENT INPUT AND OUTPUT SCHEMATIC DIAGRAMS



	R1/R2	R3
HVD20, 23	9 kΩ	45 kΩ
HVD21, 22, 24	36 kΩ	180 kΩ

PARAMETER MEASUREMENT INFORMATION

NOTES:

Test load capacitance includes probe and jig capacitance (unless otherwise specified).

Signal generator characteristics: rise and fall time < 6 ns, pulse rate 100 kHz, 50% duty cycle, $Z_0 = 50 \Omega$ (unless otherwise specified)

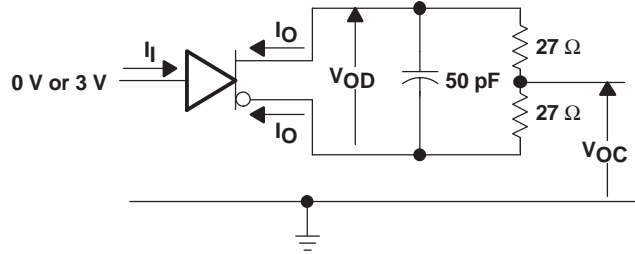


Figure 1. Driver Test Circuit, V_{OD} and V_{OC} Without Common-Mode Loading

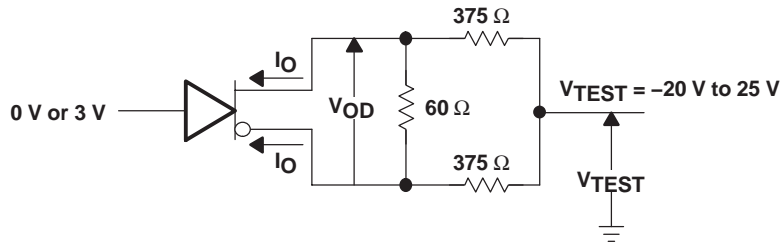


Figure 2. Driver Test Circuit, V_{OD} With Common-Mode Loading

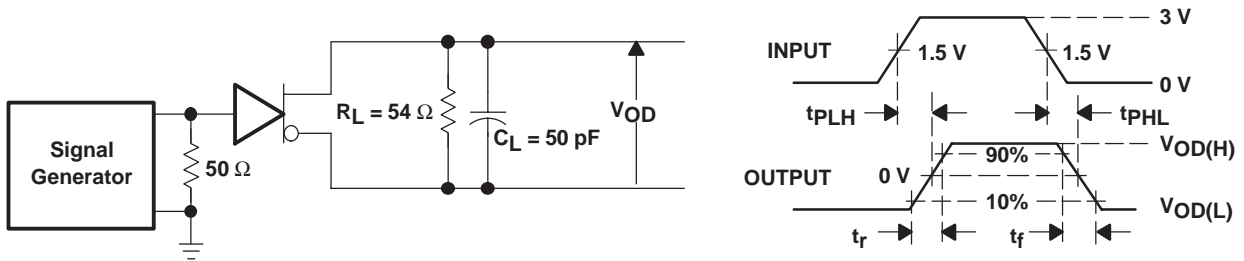


Figure 3. Driver Switching Test Circuit and Waveforms

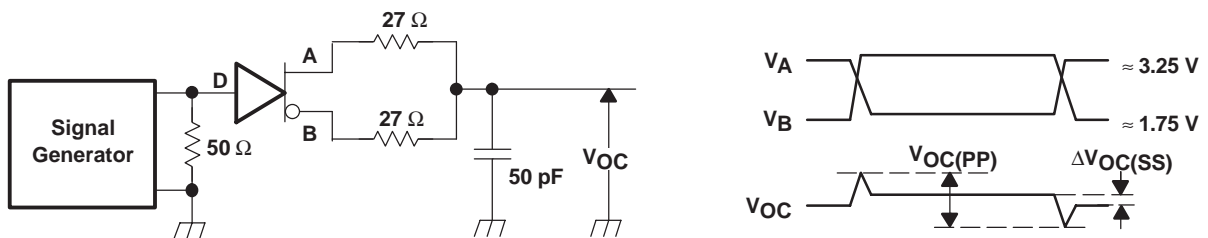
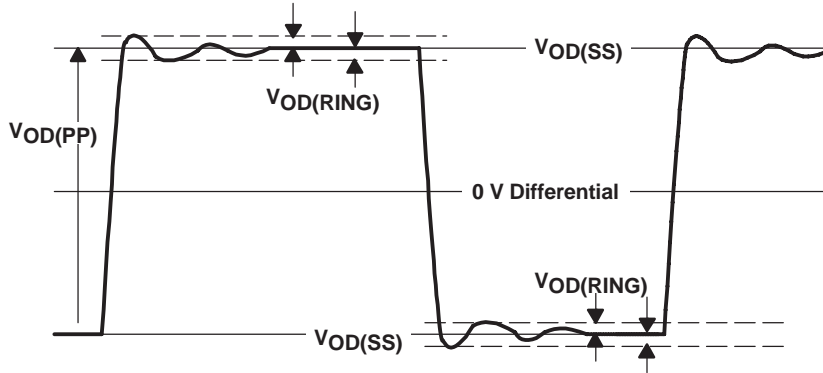


Figure 4. Driver V_{OC} Test Circuit and Waveforms



NOTE: $V_{OD(RING)}$ is measured at four points on the output waveform, corresponding to overshoot and undershoot from the $V_{OD(H)}$ and $V_{OD(L)}$ steady state values.

Figure 5. $V_{OD(RING)}$ Waveform and Definitions

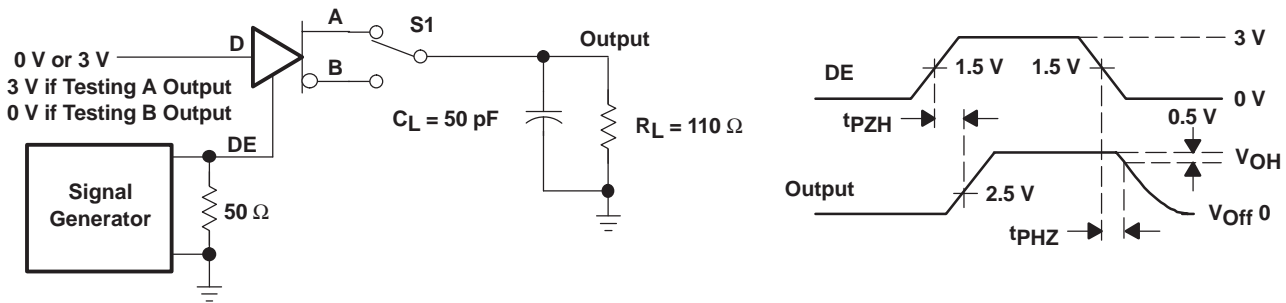


Figure 6. Driver Enable/Disable Test, High Output

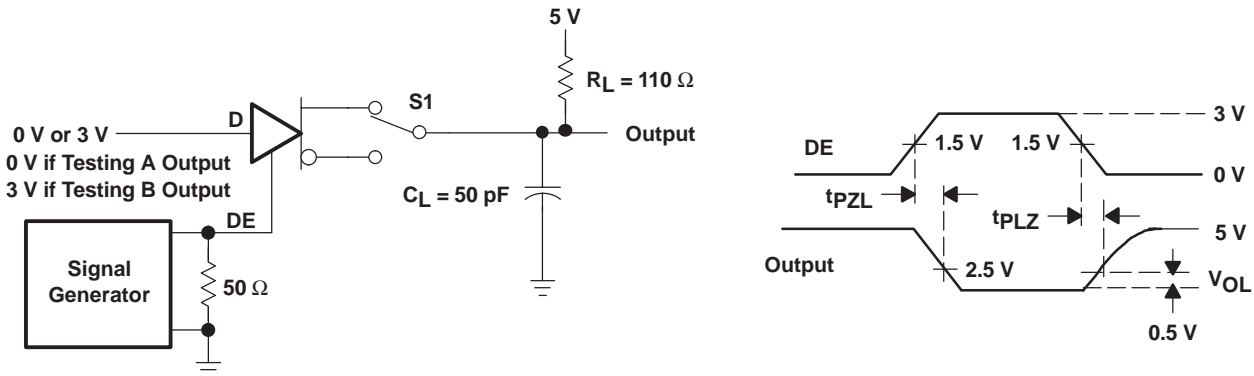


Figure 7. Driver Enable/Disable Test, Low Output

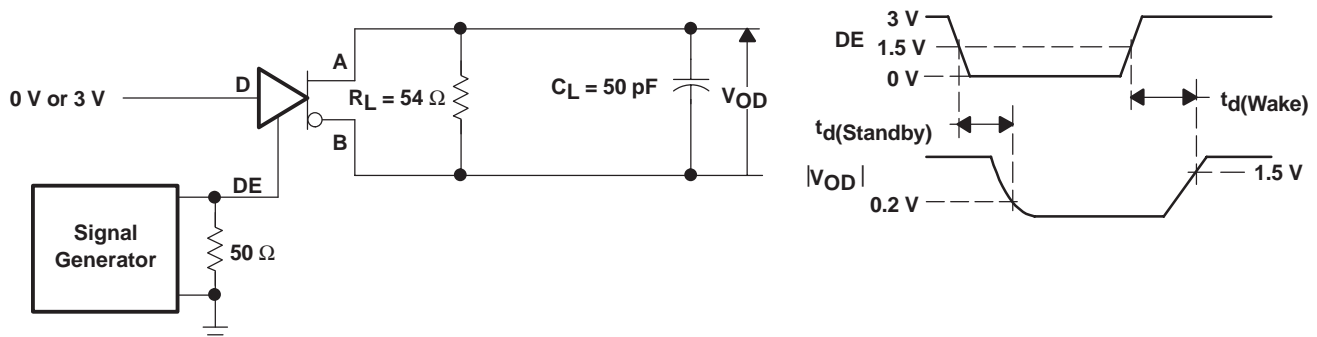


Figure 8. Driver Standby/Wake Test Circuit and Waveforms

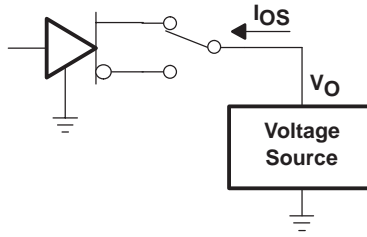


Figure 9. Driver Short-Circuit Test

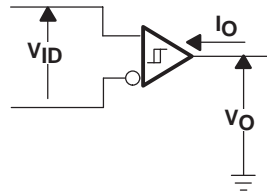


Figure 10. Receiver DC Parameter Definitions

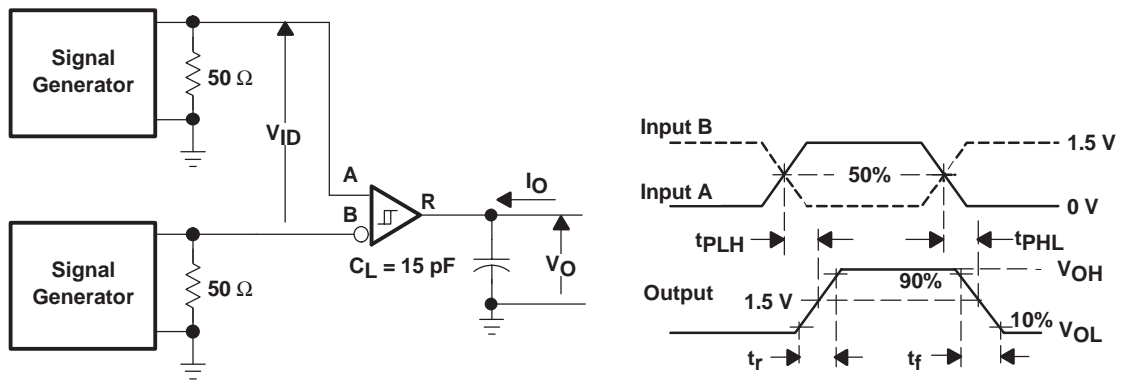


Figure 11. Receiver Switching Test Circuit and Waveforms

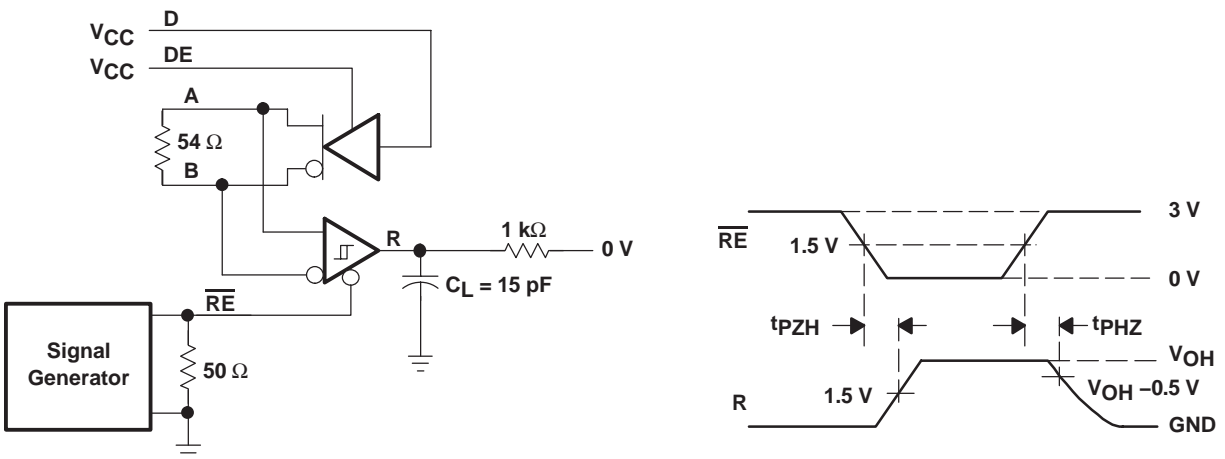


Figure 12. Receiver Enable Test Circuit and Waveforms, Data Output High

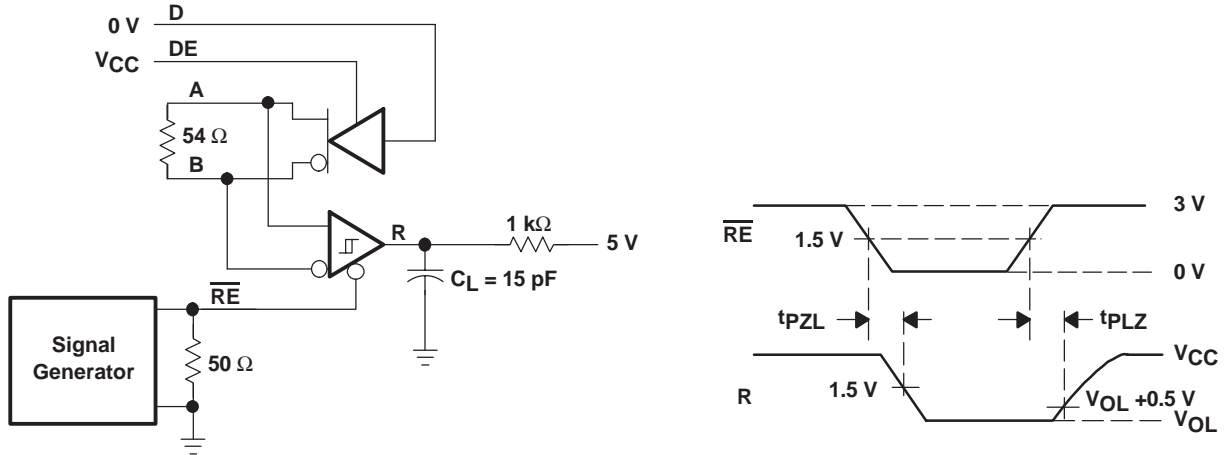


Figure 13. Receiver Enable Test Circuit and Waveforms, Data Output Low

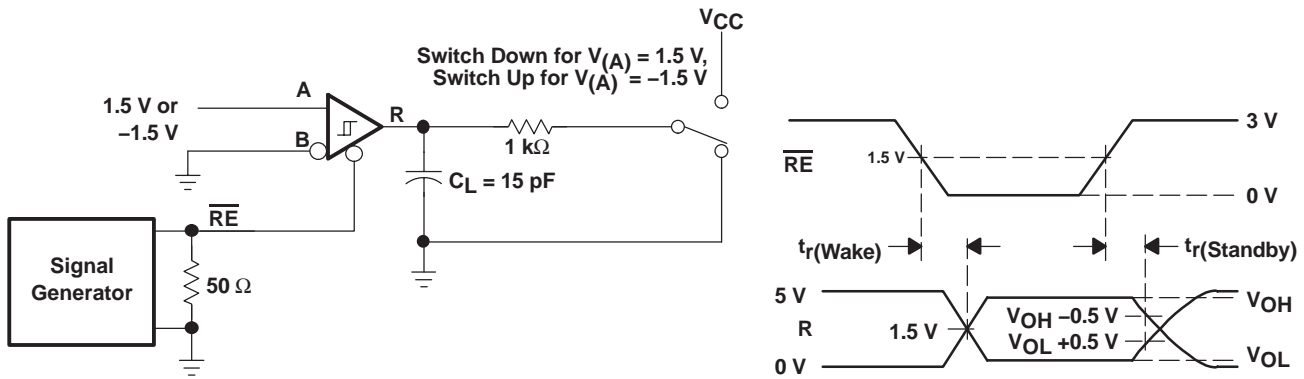


Figure 14. Receiver Standby and Wake Test Circuit and Waveforms

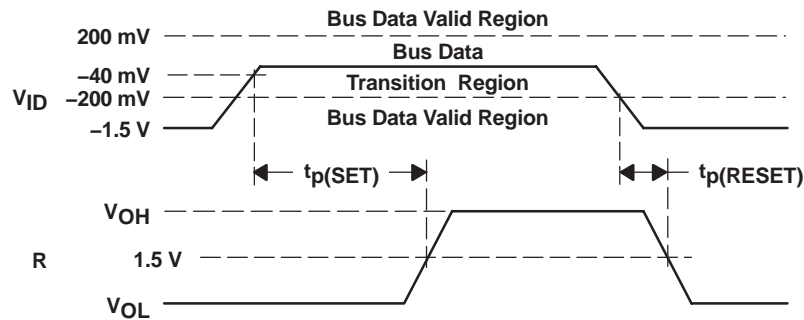


Figure 15. Receiver Active Failsafe Definitions and Waveforms

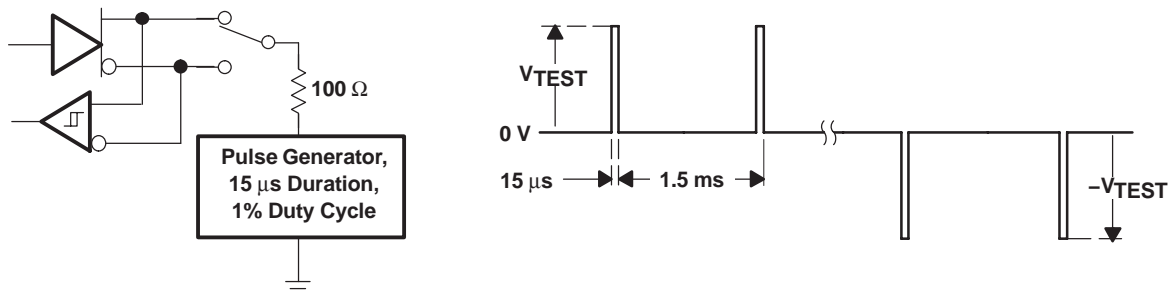
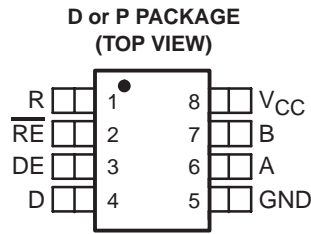
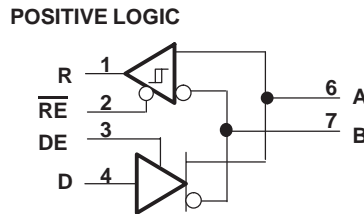


Figure 16. Test Circuit and Waveforms, Transient Overvoltage Test

PIN ASSIGNMENTS



LOGIC DIAGRAM



TYPICAL CHARACTERISTICS

**HVD20, HVD23
BUS PIN CURRENT
VS
BUS PIN VOLTAGE**

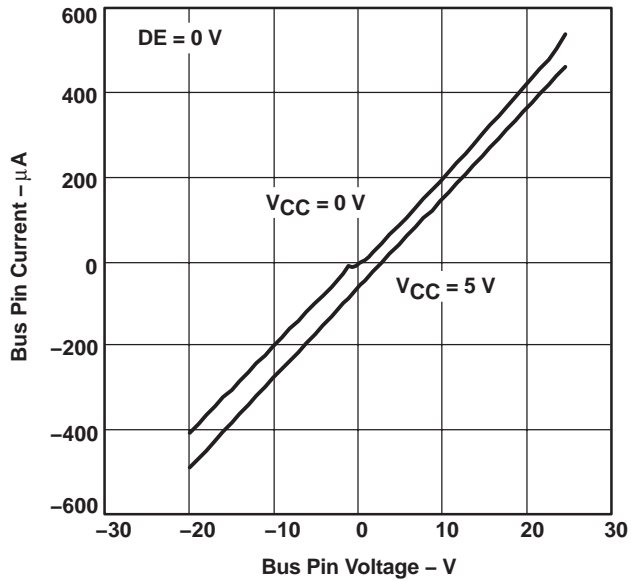


Figure 17

**HVD21, HVD22, HVD24
BUS PIN CURRENT
VS
BUS PIN VOLTAGE**

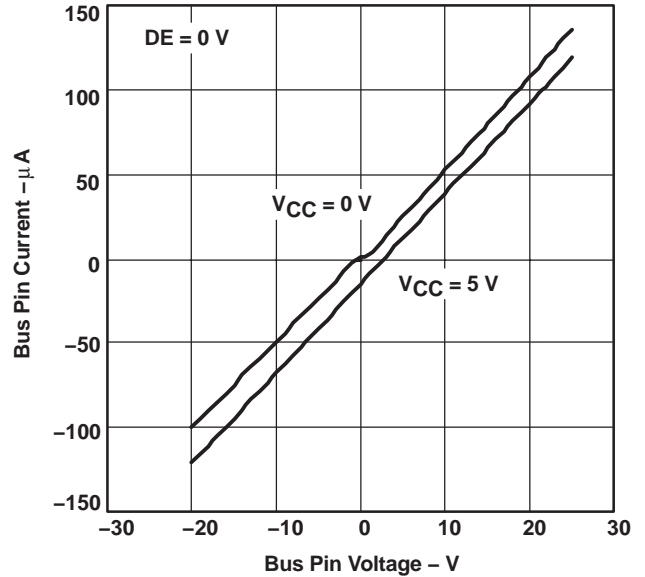


Figure 18

SUPPLY CURRENT
 VS
 SIGNALING RATE

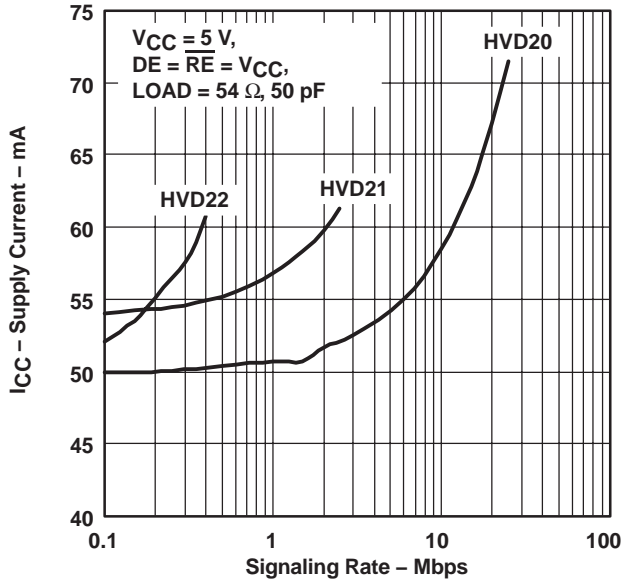


Figure 19

DRIVER DIFFERENTIAL OUTPUT VOLTAGE
 VS
 DRIVER LOAD CURRENT

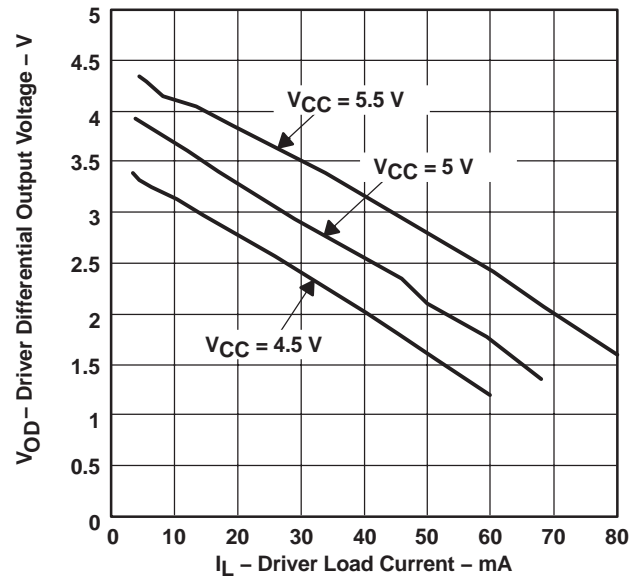


Figure 20

RECEIVER OUTPUT VOLTAGE
 VS
 DIFFERENTIAL INPUT VOLTAGE

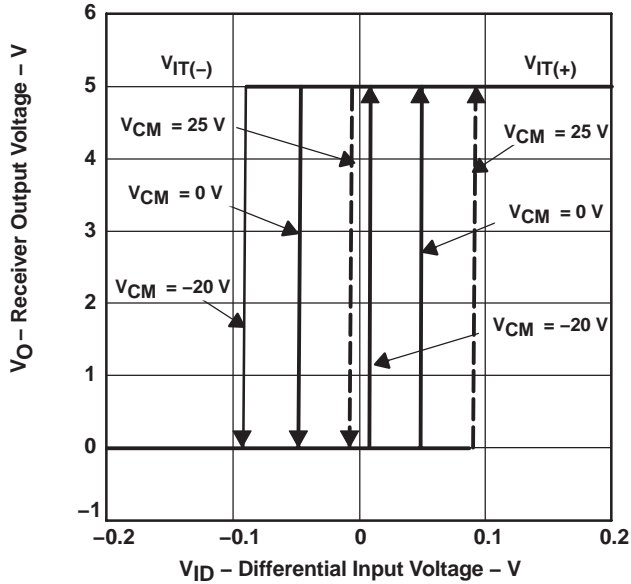


Figure 21

HVD20, HVD23
 PEAK-TO-PEAK JITTER
 VS
 CABLE LENGTH

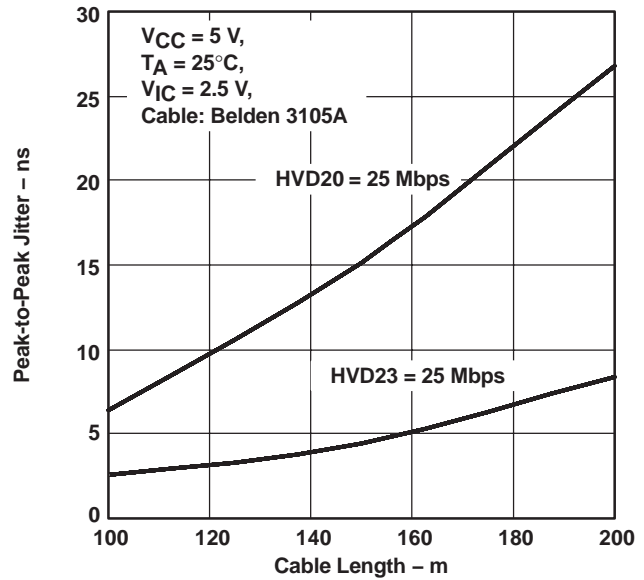


Figure 22

HVD20, HVD21, HVD23, HVD24
PEAK-TO-PEAK JITTER
VS
CABLE LENGTH

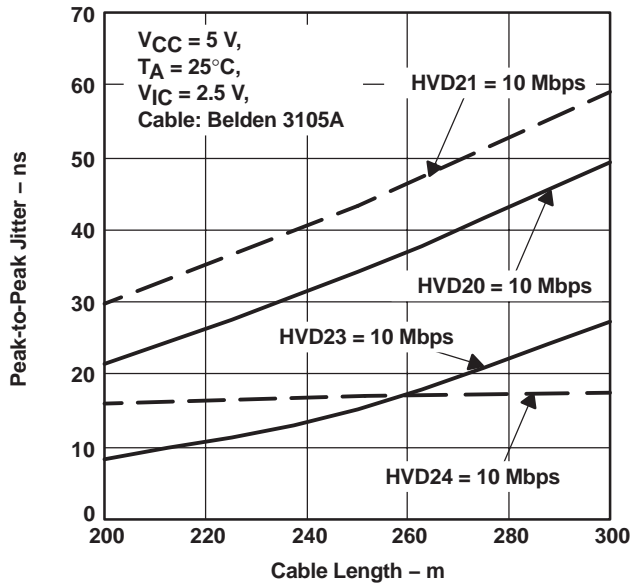


Figure 23

HVD20, HVD23
PEAK-TO-PEAK JITTER
VS
SIGNALING RATE

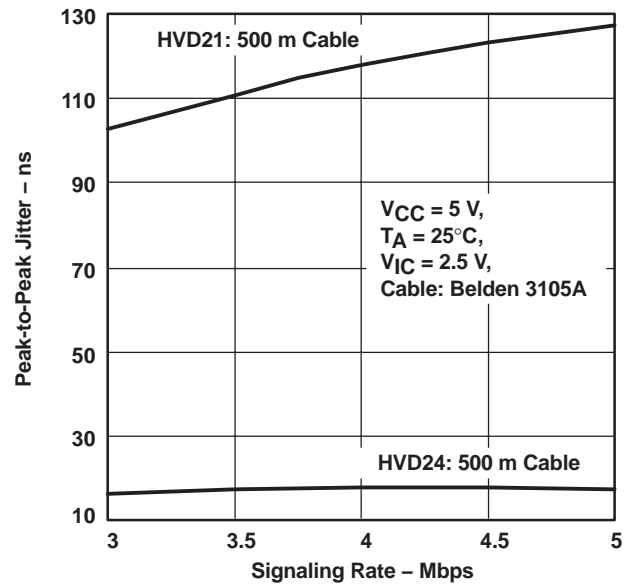


Figure 24

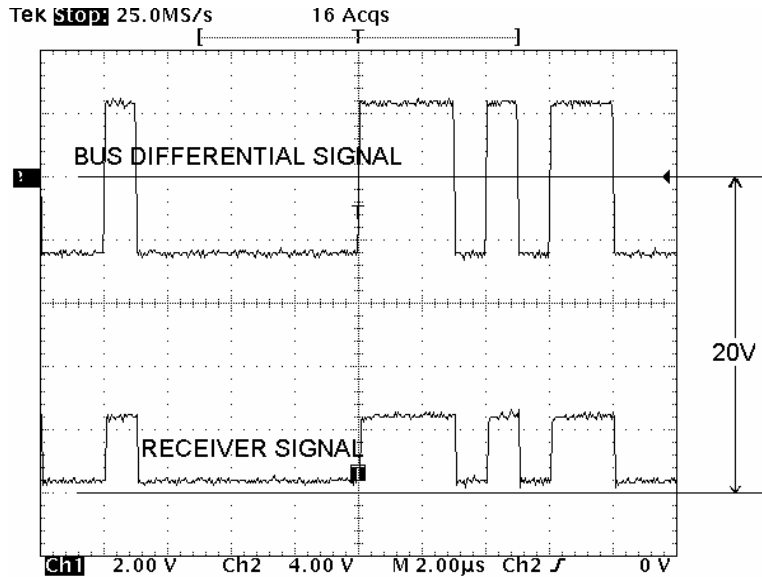


Figure 26. HVD22 Receiver Operation With 20-V Offset on Input Signal

$H(s) = k_0 \left[(1-k_1) + \frac{k_1 p_1}{(s + p_1)} \right] \left[(1-k_2) + \frac{k_2 p_2}{(s + p_2)} \right] \left[(1-k_3) + \frac{k_3 p_3}{(s + p_3)} \right]$	k0 (DC loss)	p1 (MHz)	k1	p2 (MHz)	k2	p3 (MHz)	k3
Similar to 160m of Belden 3105A	0.95	0.25	0.3	3.5	0.5	15	1
Similar to 250m of Belden 3105A	0.9	0.25	0.4	3.5	0.7	12	1
Similar to 500m of Belden 3105A	0.8	0.25	0.6	2.2	1	8	1
Similar to 1000m of Belden 3105A	0.6	0.3	1	3	1	6	1

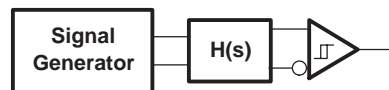


Figure 27. Cable Attenuation Model for Jitter Measurements

INTEGRATED RECEIVER EQUALIZATION USING THE HVD23

Figure 28 illustrates the benefits of integrated receiver equalization as implemented in the HVD23 transceiver. In this test setup, a differential signal generator applied a signal voltage at one end of the cable, which was Belden 3105A twisted-pair shielded cable. The test signal was a pseudo-random bit stream (PRBS) of nonreturn-to-zero (NRZ) data. Channel 1 (top) shows the eye-pattern of the differential voltage at the receiver inputs (after the cable attenuation). Channel 2 (bottom) shows the output of the receiver.

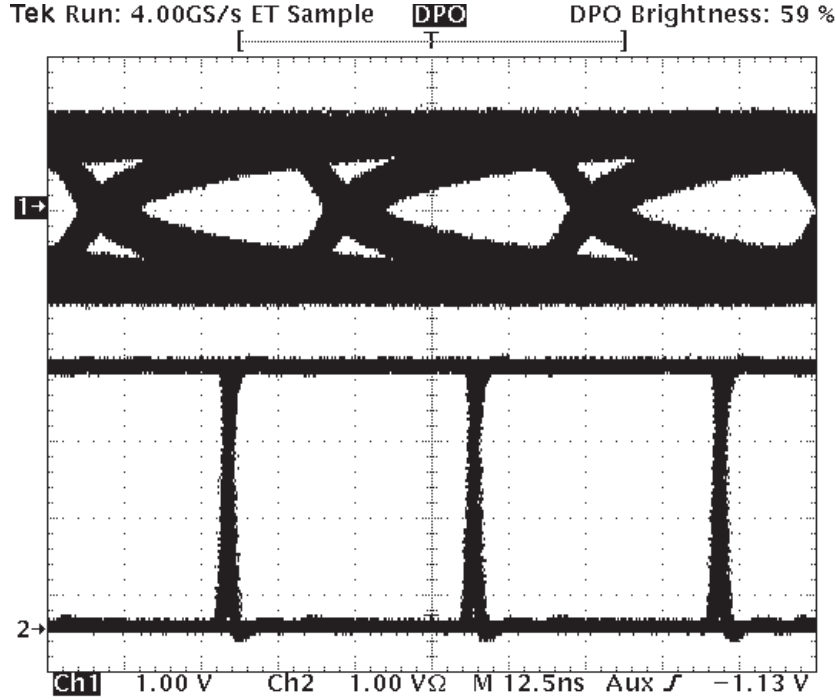


Figure 28. HVD23 Receiver Performance at 25 Mbps Over 150 Meter Cable

INTEGRATED RECEIVER EQUALIZATION USING THE HVD24

Figure 29 illustrates the benefits of integrated receiver equalization as implemented in the HVD24 transceiver. In this test setup, a differential signal generator applied a signal voltage at one end of the cable, which was Belden 3105A twisted-pair shielded cable. The test signal was a pseudo-random bit stream (PRBS) of nonreturn-to-zero (NRZ) data. Channel 1 (top) shows the eye-pattern of the bit stream. Channel 2 (middle) shows the eye-pattern of the differential voltage at the receiver inputs (after the cable attenuation). Channel 3 (bottom) shows the output of the receiver.

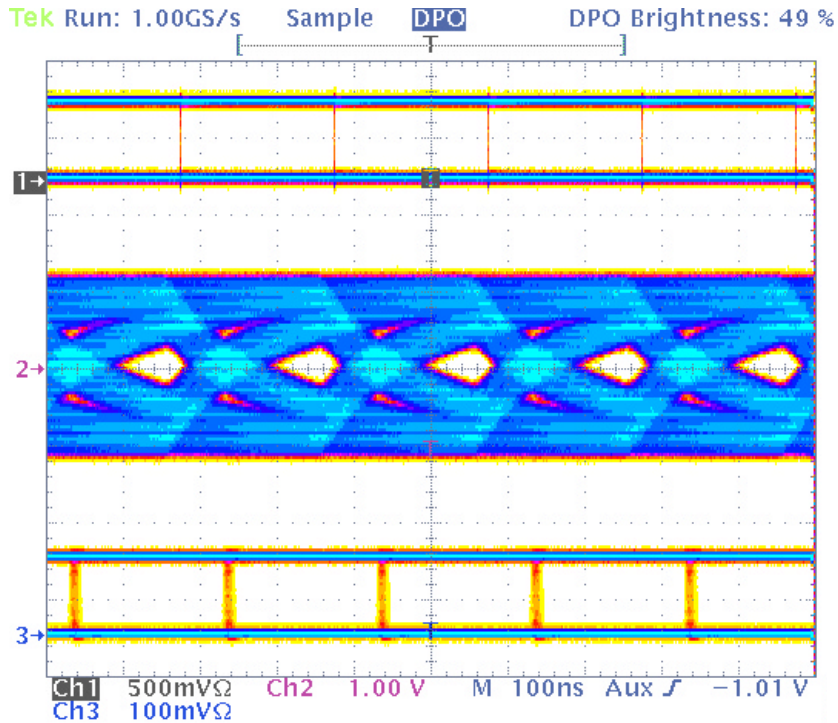


Figure 29. HVD24 Receiver Performance at 5 Mbps Over 500 Meter Cable

NOISE CONSIDERATIONS FOR EQUALIZED RECEIVERS

The simplest way of overcoming the effects of cable losses is to increase the sensitivity of the receiver. If the maximum attenuation of frequencies of interest is 20 dB, increasing the receiver gain by a factor of ten compensates for the cable. However, this means that both signal and noise are amplified. Therefore, the receiver with higher gain is more sensitive to noise and it is important to minimize differential noise coupling to the equalized receiver.

Differential noise is created when conducted or radiated noise energy generates more voltage on one line of the differential pair than the other. For this to occur from conducted or electric far-field noise, the impedance to ground of the lines must differ.

For noise frequency out to 50 MHz, the input traces can be treated as a lumped capacitance if the receiver is approximately 10 inches or less from the connector. Therefore, matching impedance of the lines is accomplished by matching the lumped capacitance of each.

The primary factors that affect the capacitance of a trace are in length, thickness, width, dielectric material, distance from the signal return path, stray capacitance, and proximity to other conductors. It is difficult to match each of the variables for each line of the differential pair exactly, but a reasonable effort to do so keeps the lines balanced and less susceptible to differential noise coupling.

Another source of differential noise is from near-field coupling. In this situation, an assumption of equal noise-source impedance cannot be made as in the far-field. Familiarly known as crosstalk, more energy from a nearby signal is coupled to one line of the differential pair. Minimization of this differential noise is accomplished by keeping the signal pair close together and physical separation from high-voltage, high-current, or high-frequency signals.

In summary, follow these guidelines in board layout for keeping differential noise to a minimum.

- Keep the differential input traces short.
- Match the length, physical dimensions, and routing of each line of the pair.
- Keep the lines close together.
- Match components connected to each line.
- Separate the inputs from high-voltage, high-frequency, or high-current signals.

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN65HVD20D	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN65HVD20DG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN65HVD20DR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN65HVD20DRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN65HVD20P	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN65HVD20PE4	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN65HVD21D	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN65HVD21DG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN65HVD21DR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN65HVD21DRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN65HVD21P	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN65HVD21PE4	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN65HVD22D	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN65HVD22DG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN65HVD22DR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN65HVD22DRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN65HVD22P	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN65HVD22PE4	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN65HVD23D	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN65HVD23DG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN65HVD23DR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN65HVD23DRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN65HVD23P	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN65HVD23PE4	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN65HVD24D	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN65HVD24DG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN65HVD24DR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN65HVD24DRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN65HVD24P	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN65HVD24PE4	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBsolete: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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TAPE AND REEL INFORMATION



QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN65HVD20DR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
SN65HVD21DR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
SN65HVD22DR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
SN65HVD23DR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
SN65HVD24DR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN65HVD20DR	SOIC	D	8	2500	340.5	338.1	20.6
SN65HVD21DR	SOIC	D	8	2500	340.5	338.1	20.6
SN65HVD22DR	SOIC	D	8	2500	340.5	338.1	20.6
SN65HVD23DR	SOIC	D	8	2500	340.5	338.1	20.6
SN65HVD24DR	SOIC	D	8	2500	340.5	338.1	20.6

P (R-PDIP-T8)

PLASTIC DUAL-IN-LINE PACKAGE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. Falls within JEDEC MS-001 variation BA.

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